

L Number	Hits	Search Text	DB	Time stamp
17	246233	resistor	USPAT; US-PGPUB	2003/05/01 20:30
18	105089	resistor and gate	USPAT; US-PGPUB	2003/05/01 20:30
19	77302	((resistor and gate) and (via contact hole recess trench))	USPAT; US-PGPUB	2003/05/01 20:30
20	36105	((resistor and gate) and (via contact hole recess trench)) and (semiconductor substrate wafer)	USPAT; US-PGPUB	2003/05/01 20:30
21	32549	((resistor and gate) and (via contact hole recess trench)) and (semiconductor substrate wafer)) and (source drain)	USPAT; US-PGPUB	2003/05/01 20:30
23	352	((resistor and gate) and (via contact hole recess trench)) and (semiconductor substrate wafer)) and (source drain)) and ((dummy sacrificial temporary) near5 gate)	USPAT	2003/05/01 19:28
22	28870	((resistor and gate) and (via contact hole recess trench)) and (semiconductor substrate wafer)) and (source drain)	USPAT	2003/05/01 19:39
24	2273	((resistor and gate) and (via contact hole recess trench)) and (semiconductor substrate wafer)) and (source drain)) and 438/\$.ccls.	USPAT	2003/05/01 19:48
25	244923	resistor	EPO; JPO; DERWENT; IBM_TDB	2003/05/01 20:30
26	23288	resistor and gate	EPO; JPO; DERWENT; IBM_TDB	2003/05/01 20:30
27	6955	((resistor and gate) and (via contact hole recess trench))	EPO; JPO; DERWENT; IBM_TDB	2003/05/01 20:30
28	1553	((resistor and gate) and (via contact hole recess trench)) and (semiconductor substrate wafer)	EPO; JPO; DERWENT; IBM_TDB	2003/05/01 20:30
29	909	((resistor and gate) and (via contact hole recess trench)) and (semiconductor substrate wafer)) and (source drain)	EPO; JPO; DERWENT; IBM_TDB	2003/05/01 20:31